

ABSTRACT OF THE DISCLOSURE

The object of the present invention is to realize a semiconductor device enabling a flip chip connection without use of underfill.

The present invention provides a semiconductor device comprising a semiconductor element having a plurality of circuit electrodes disposed thereon and a circuit surface coated with a protecting film, a stress relaxation layer made by coating a cured thermoplastic resin onto the protecting film of the circuit surface of the semiconductor element so as to expose the circuit electrodes and curing it and having an inclination in the edge portion thereof, a wiring layer consisting of a plurality of wirings connected to each of the circuit electrodes and disposed so as to make an electrical connection from the circuit electrodes, via the edge portion of the stress relaxation layer, and to a desired portion on the surface of the stress relaxation layer, a protecting film provided thereon, and an external connection terminal.